



## Material Content Data Sheet



Sales Product Name	ESD8V0R1B-02LRH E6327			Issued		29. August 2013		
MA#	MA000457474							
Package	PG-TSLP-2-17			Weight*		0.60 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.06		579	
	noble metal	gold	7440-57-5	0.001	0.22		2244	
	inorganic material	silicon	7440-21-3	0.017	2.74	3.02	27400	30223
leadframe	non noble metal	nickel	7440-02-0	0.138	22.93	22.93	229258	229258
wire	noble metal	gold	7440-57-5	0.006	0.97	0.97	9731	9731
encapsulation	organic material	carbon black	1333-86-4	0.004	0.69		6886	
	plastics	epoxy resin	-	0.056	9.30		92965	
	inorganic material	silicondioxide	60676-86-0	0.355	58.88	68.87	588781	688632
leadfinish	noble metal	gold	7440-57-5	0.010	1.60	1.60	16011	16011
plating	noble metal	silver	7440-22-4	0.016	2.61	2.61	26145	26145
*deviation	< 10%				Sum in total:		100,00	1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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